



## Product Change Notification - KMIO-24FXKZ027 (Printer Friendly)

**Date:**

10 Nov 2017

**Product Category:**

Capacitive Touch Sensors; Temperature Sensors; Current And Power Measurement ICs

**Notification subject:**

CCB 2719 Final Notice: Qualification of G700Y mold compound for selected product available on 10L VDFN package at ANAP assembly site.

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of G700Y mold compound for selected product available on 10L VDFN package at ANAP assembly site.

**Pre Change:**

Assembled using GE7470LA mold compound.

**Post Change:**

Assembled using G700Y mold compound.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	Amkor Technology Philippine INC.(ANAP)	Amkor Technology Philippine INC.(ANAP)
<b>Wire material</b>	Au wire	Au wire
<b>Die attach material</b>	AMK-06	AMK06
<b>Molding compound material</b>	GE7470LA	G700Y

<b>Lead frame material</b>	C194	C194
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**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To Improve on-time delivery performance by qualifying G700Y mold compound at ANAP assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

December 10, 2017 (date code: 1750)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2016				->	November 2017				December 2017			
	31	32	33	34		44	45	46	47	48	49	50	51
Workweek													
Initial PCN Issue Date				X									
Qual Report Availability							X						
Final PCN Issue Date							X						
Estimated Implementation Date											X		

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**

**August 24, 2016:** Issued initial notification.

**November 10, 2017:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date on December 10, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KMIO-24FXKZ027\\_Affected CPN.pdf](#)

[PCN\\_KMIO-24FXKZ027\\_Qual Report.pdf](#)

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